

**IV. AMENDMENTS TO THE CLAIMS**

1. (Currently Amended) An adhesive tape applying method for placing an applicator member in contact with a surface of adhesive tape and applying the adhesive tape to a surface of a workpiece held by holding means, said method comprising:

a step of applying said adhesive tape to said workpiece held by the holding means, while holding said adhesive tape between said applicator member and said holding means and moving the applicator member and said holding means relative to each other, and while vibrating said adhesive tape.

2. (Original) An adhesive tape applying method as defined in claim 1, wherein vibration is applied to said applicator member.

3. (Original) An adhesive tape applying method as defined in claim 1, wherein vibration is applied to holding means for receiving and holding said workpiece.

4. (Original) An adhesive tape applying method as defined in claim 1, further comprising:

a step of applying said adhesive tape to said workpiece while heating said adhesive tape.

5. (Original) An adhesive tape applying method as defined in claim 4, wherein said adhesive tape is heated by heating holding means.

6. (Original) An adhesive tape applying method as defined in claim 1, wherein said applicator member is one or both of an applicator roller and an applicator edge member.

7. (Original) An adhesive tape applying method as defined in claim 1,

wherein said adhesive tape is in strip form.

8. (Original) An adhesive tape applying method as defined in claim 1, wherein said adhesive tape is in label form shaped substantially to a shape of said workpiece beforehand.

9. (Original) An adhesive tape applying method as defined in claim 1, wherein said workpiece is a semiconductor wafer.

10. (Currently Amended) An adhesive tape applying apparatus for applying adhesive tape to a surface of a workpiece, comprising:  
holding means for receiving and holding said workpiece;  
tape feed means for feeding the adhesive tape toward the workpiece held by said holding means;  
applying means for placing an applicator member in contact with a surface of the adhesive tape and applying the adhesive tape to a surface of the workpiece; and

first vibration generating means for vibrating said applying means;  
wherein said adhesive tape is applied to the workpiece held by said holding means, while said adhesive tape is held between said applying means and said holding means moved relative to each other, and while said adhesive tape is vibrated by said first vibration generating means.

11. (Original) An adhesive tape applying apparatus as defined in claim 10, further comprising heating means for heating said holding means.

12. (Original) An adhesive tape applying apparatus as defined in claim 10, further comprising cutting means for cutting the adhesive tape applied to said workpiece, substantially to a shape of said workpiece.

13. (Original) An adhesive tape applying apparatus as defined in claim

10, wherein said first vibration generating means is electromagnetically operable.

14. (Original) An adhesive tape applying apparatus as defined in claim 10, wherein said first vibration generating means is constructed for rotating an eccentric weight.

15. (Original) An adhesive tape applying apparatus as defined in claim 10, further comprising second vibration generating means for vibrating said holding means.

16. (Original) An adhesive tape applying apparatus as defined in claim 15, wherein said second vibration generating means is electromagnetically operable.

17. (Original) An adhesive tape applying apparatus as defined in claim 15, wherein said second vibration generating means is constructed for rotating an eccentric weight.

18. (Original) An adhesive tape applying apparatus as defined in claim 10, wherein said adhesive tape is in strip form.

19. (Original) An adhesive tape applying apparatus as defined in claim 10, wherein said adhesive tape is in label form shaped substantially to a shape of said workpiece beforehand.

20. (Original) An adhesive tape applying apparatus as defined in claim 10, wherein said workpiece is a semiconductor wafer.